

03-27-2001

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To the Honorable Commissioner of Pa

101649779

1. Name of conveying party(ies):

KANG, Seong-goo
MIN, Byoung-jun
CHAE, Hyo-geun
BANG, Jeong-ho

3/14/01

2. Name and address of receiving party(ies):

Name: SAMSUNG ELECTRONICS CO., LTD.

Address: 416, Maetan-dong, Paldal-gu,

JC986 U.S. PTO
09/805212
03/14/01

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

City: Suwon-city, Kyungki-do

State/Prov.:

Country: Republic of Korea

ZIP:

Execution Date: February 22, 2001

Additional name(s) & address(es)

☐ Yes☒ No

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is: February 22, 2001

Patent Application No.

Filing date

B. Patent No.(s)

NEW

MARCH 14, 2001

09805212

03/15/2001 TBESHAN1 00000044 09805212

02 FC:581

40.00 OP

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: ADAM C. VOLENTINE

Registration No. 33289

Address: JONES VOLENTINE, LLC

12200 SUNRISE VALLEY DRIVE, SUITE 150

City: RESTON

State/Prov.: VA

Country: U.S.A.

ZIP: 20191

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☐ Authorized to be charged to deposit account

8. Deposit account number:

50-0238

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

ADAM C. VOLENTINE

Name of Person Signing

Signature

MARCH 14, 2001

Date

3

Total number of pages including cover sheet, attachments, and

PATENT

REEL: 011608 FRAME: 0072

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Insert Name(s)
of Inventor(s)

KANG, Seong-goo

MIN, Byoung-jun

CHAE, Hyo-geun

and

BANG, Jeong-ho

the undersigned hereby sell(s) and assign(s) to

Insert Name(s)
of Assignee(s)

SAMSUNG ELECTRONICS CO., LTD.

Address

of 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Korea

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

Title of
Invention

SEMICONDUCTOR PACKAGE TESTING EQUIPMENT INCLUDING LOADER HAVING PACKAGE
GUIDER AND METHOD OF LOADING A SEMICONDUCTOR PACKAGE ONTO A TEST SOCKET AS

ALIGNED THEREWITH

Date of Signing
of Application

for which an application for patent in the United States of America has been executed by the undersigned

on February 22, 2001

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) to Adam C. Volentine, Reg. No. 33,289, and the firm of JONES VOLENTINE, L.L.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date 22. Feb. 2001, Name of Inventor Seong-goo Kang
Seong-goo Kang
Date 22. Feb. 2001, Name of Inventor Byoung-jun Min
Byoung-jun Min
Date 22. Feb. 2001, Name of Inventor Hyo-geun Chae
Hyo-geun Chae
Date 22. Feb. 2001, Name of Inventor Jeong-ho Bang
Jeong-ho Bang
Date _____, Name of Inventor _____

(Note regarding Witnessing and/or Acknowledgment: Acknowledgment before a United States Consul is preferred but not required. If not acknowledged, then it is recommended that the execution by the Inventor(s) be witnessed by at least two witnesses who sign here. However, the current practice of the U.S. Patent and Trademark Office is to record an Assignment even if it has not been acknowledged and/or witnessed.)

Witness _____

Witness _____

ACKNOWLEDGMENT

} ss

This _____ day of _____, 19____, before me personally came the above-named

_____ to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

Official Signature

SEAL

Official Title

Applicant Reference No.: SS-14582-US Atty Docket No.: SEC.781

Serial No.: _____ Filing Date: _____